



RMB2F THRU RMB10F

Voltage Range - 200 to 1000 Volts Current - 0.5/0.8 Ampere

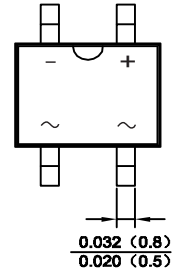
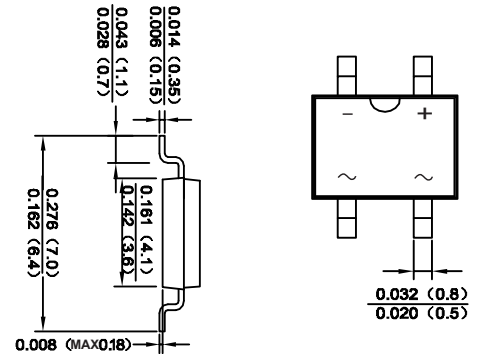
GLASS PASSIVATED FAST RECOVERY BRIDGE RECTIFIERS

Features

- ◆ Ideal for printed circuit board
- ◆ Reliable low cost construction utilizing molded plastic technique
- ◆ High temperature soldering guaranteed: 260°C /10 seconds at 5 lbs., (2.3kg) tension Small size, simple installation
- ◆ Leads solderable per MIL-STD-202, Method 208
- ◆ High surge current capability
- ◆ Glass passivated chip junction
- ◆ Green compound(halogen&Sb2O3 free)

MBF

ROHS
COMPLIANT



Mechanical Data

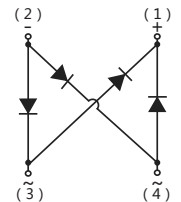
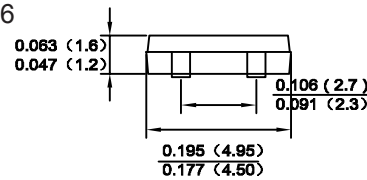
Case : JEDEC MBF Molded plastic body

Terminals : Solder plated, solderable per MIL-STD-750, Method 2026

Polarity : Polarity symbol marking on body

Mounting Position : Any

Weight : 0.0026 ounce, 0.075 grams



Maximum Ratings And Electrical Characteristics

Dimensions in inches and (millimeters)

Ratings at 25 °C ambient temperature unless otherwise specified.

Single phase half-wave 60Hz, resistive or inductive load, for capacitive load current derate by 20%.

Parameter	SYMBOLS	MDD	MDD	MDD	MDD	MDD	UNITS
		RMB2F	RMB4F	RMB6F	RMB8F	RMB10F	
Marking Code							
Maximum repetitive peak reverse voltage	V_{RRM}	200	400	600	800	1000	V
Maximum RMS voltage	V_{RMS}	140	280	420	560	700	V
Maximum DC blocking voltage	V_{DC}	200	400	600	800	1000	V
Maximum average forward rectified current On glass-epoxy P.C.B.(Note1) On aluminum substrate(Note2)	$I_{F(AV)}$			0.5 0.8			A
Peak forward surge current, 8.3ms single half sine-wave superimposed on rated load (JEDEC Method)	I_{FSM}			30			A
Maximum instantaneous forward voltage drop per leg at 0.4A	V_F			1.3			V
Maximum DC reverse current at rated DC blocking voltage $T_A=25^{\circ}C$ $T_A=100^{\circ}C$	I_R			5 0.5			μA mA
Maximum reverse recovery time	t_{rr}	150		250		200	ns
Typical thermal resistance Note3	$R_{\theta JL}$ $R_{\theta JA}$			30 88			$^{\circ}C/W$
Operating temperature range Note4	T_J			-55 to +150			$^{\circ}C$
storage temperature range	T_{STG}			-55 to +150			$^{\circ}C$

NOTES:1. On glass epoxy P.C.B. mounted on 0.05x0.05"(1.3x1.3mm) pads.

2. On aluminum substrate P.C.B. with an area of 0.8"x0.8"(20x20mm) mounted on 0.05X0.05"(1.3X1.3mm) solder pad.

3. Thermal resistance from junction to ambient and junction to lead mounted on P.C.B. with 0.2X0.2"(5X5mm) copper pads.

4. Reverse recovery condition $I_F=0.5A, I_R=1.0A, I_{rr}=0.25A$.



Ratings And Characteristic Curves

FIG.1 FORWARD DERATING CURVE

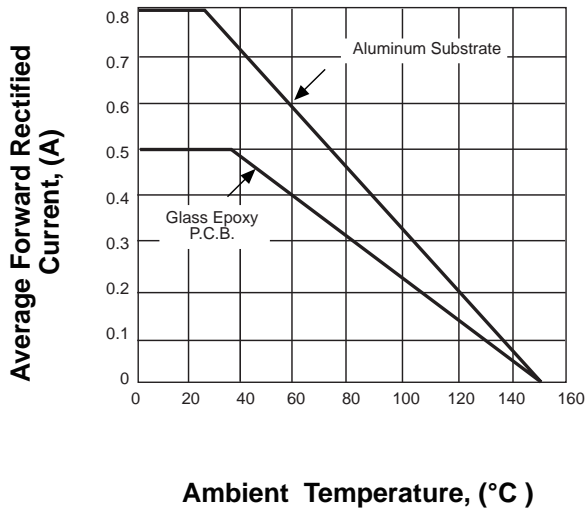


FIG.2 PEAK FORWARD SURGE CURRENT

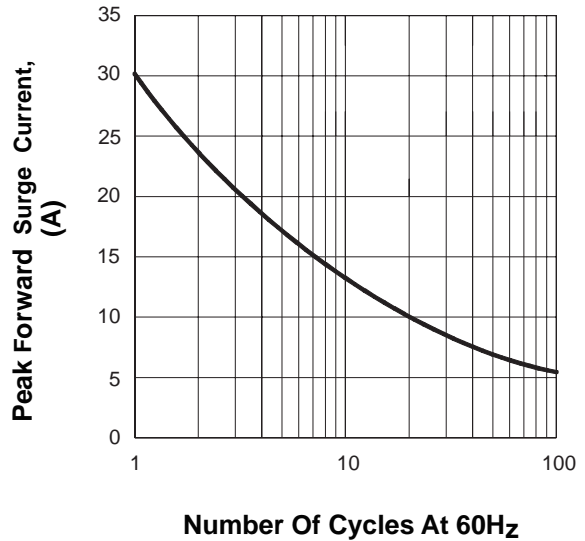


FIG.3 TYPICAL FORWARD CHARACTERISTICS

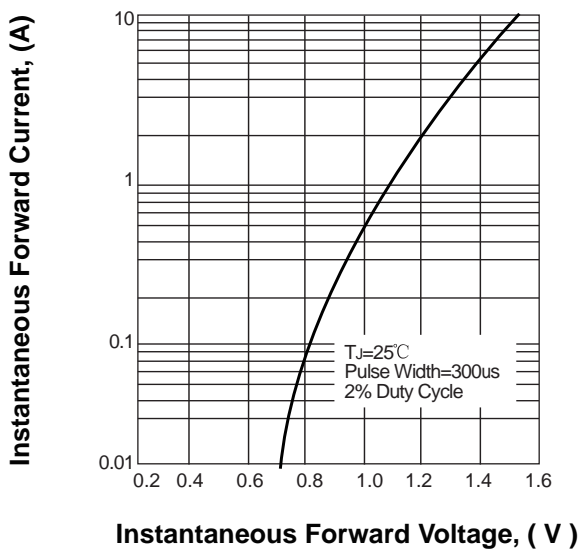
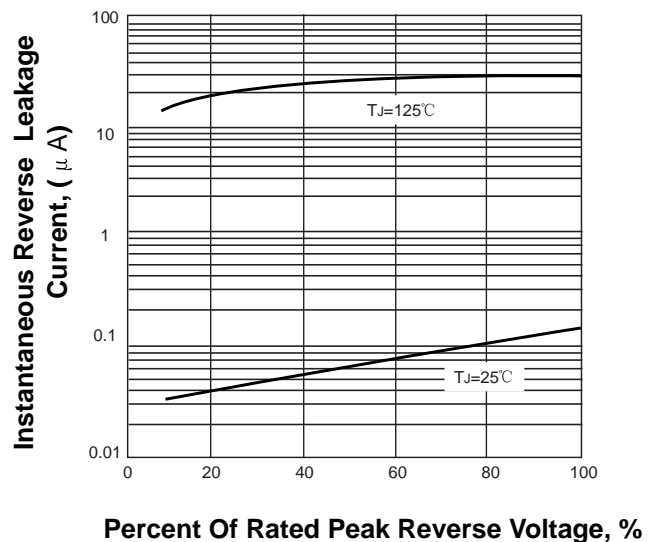


FIG.4 TYPICAL REVERSE CHARACTERISTICS



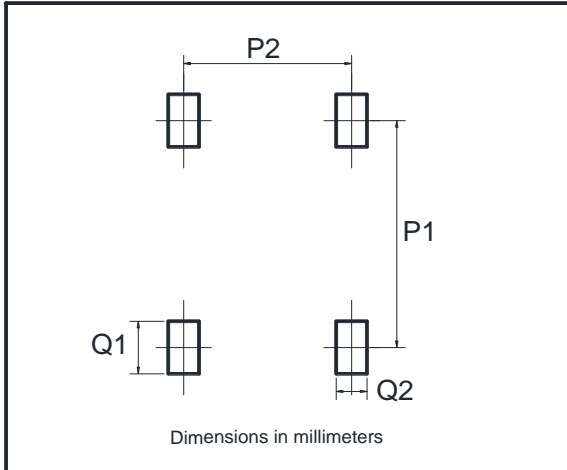
The curve above is for reference only.



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Suggested Pad Layout



Dim	Min
P1	6.00
P2	2.40
Q1	1.84
Q2	1.20